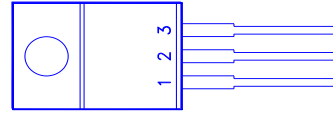
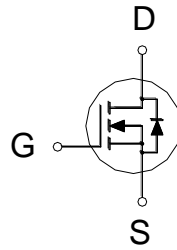


**PRODUCT SUMMARY**

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
100V	26.8mΩ	36A



1: GATE  
2: DRAIN  
3: SOURCE

**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25 ° C Unless Otherwise Noted)**

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		$V_{DS}$	100	V
Gate-Source Voltage		$V_{GS}$	±20	V
Continuous Drain Current	T <sub>C</sub> = 25 ° C	$I_D$	36	A
	T <sub>C</sub> = 100 ° C		23	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	70	
Avalanche Current		$I_{AS}$	11	
Avalanche Energy	L = 0.1mH	$E_{AS}$	6	mJ
Power Dissipation	T <sub>C</sub> = 25 ° C	$P_D$	83	W
	T <sub>C</sub> = 100 ° C		33	
Junction & Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to 150	° C

**THERMAL RESISTANCE RATINGS**

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient	R <sub>θJA</sub>		62.5	° C / W
Junction-to-Case	R <sub>θJC</sub>		1.5	

<sup>1</sup>Pulse width limited by maximum junction temperature.

**ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25 ° C, Unless Otherwise Noted)**

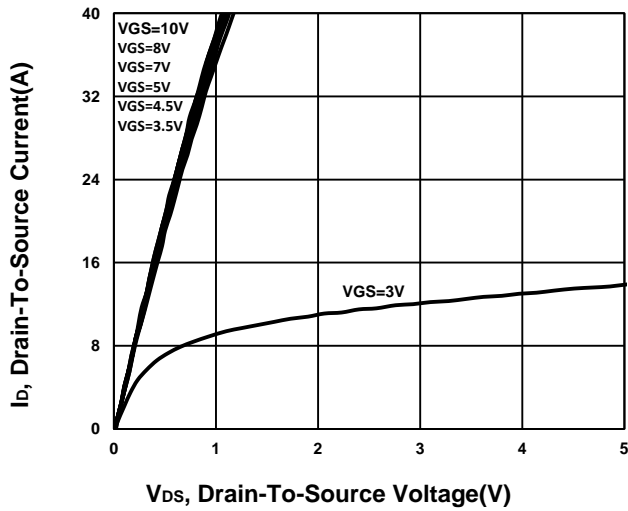
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	100			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.3	1.8	2.3	
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$			±100	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 80V, V_{GS} = 0V$			1	μA
		$V_{DS} = 80V, V_{GS} = 0V, T_J = 125 ° C$			10	
Drain-Source On-State Resistance <sup>1</sup>	$R_{DS(ON)}$	$V_{GS} = 4.5V, I_D = 10A$		23	35	mΩ
		$V_{GS} = 10V, I_D = 10A$		22	26.8	

Forward Transconductance <sup>1</sup>	$g_{fs}$	$V_{DS} = 5V, I_D = 10A$		50		S
<b>DYNAMIC</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		1910		pF
Output Capacitance	$C_{oss}$			148		
Reverse Transfer Capacitance	$C_{rss}$			87		
Gate Resistance	$R_g$	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$		0.8		$\Omega$
Total Gate Charge <sup>2</sup>	$Q_{g(VGS=10V)}$	$V_{DS} = 50V, I_D = 10A$		40		nC
	$Q_{g(VGS=4.5V)}$			21.5		
Gate-Source Charge <sup>2</sup>	$Q_{gs}$			6		
Gate-Drain Charge <sup>2</sup>	$Q_{gd}$			12		
Turn-On Delay Time <sup>2</sup>	$t_{d(on)}$		$V_{DS} = 50V, I_D \cong 10A,$ $V_{GS} = 10V, R_{GEN} = 6\Omega$		15	
Rise Time <sup>2</sup>	$t_r$			43		
Turn-Off Delay Time <sup>2</sup>	$t_{d(off)}$			45		
Fall Time <sup>2</sup>	$t_f$			37		
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T<sub>J</sub> = 25 ° C)</b>						
Continuous Current	$I_S$			36		A
Forward Voltage <sup>1</sup>	$V_{SD}$	$I_F = 10A, V_{GS} = 0V$		1.2		V
Diode Reverse Recovery Time	$t_{rr}$	$I_F = 10A, di/dt = 100A/\mu s$		31		nS
Diode Reverse Recovery Charge	$Q_{rr}$			35		nC

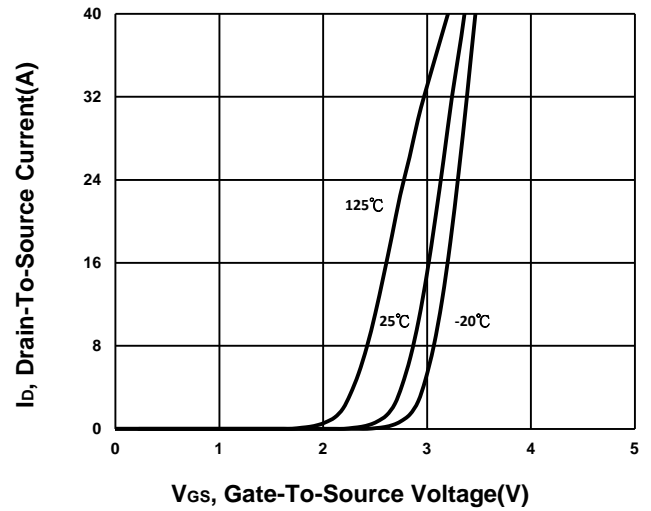
<sup>1</sup>Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

<sup>2</sup>Independent of operating temperature.

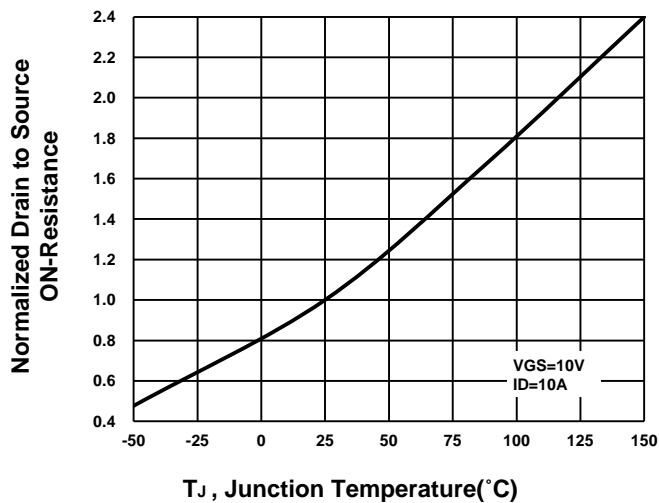
**Output Characteristics**



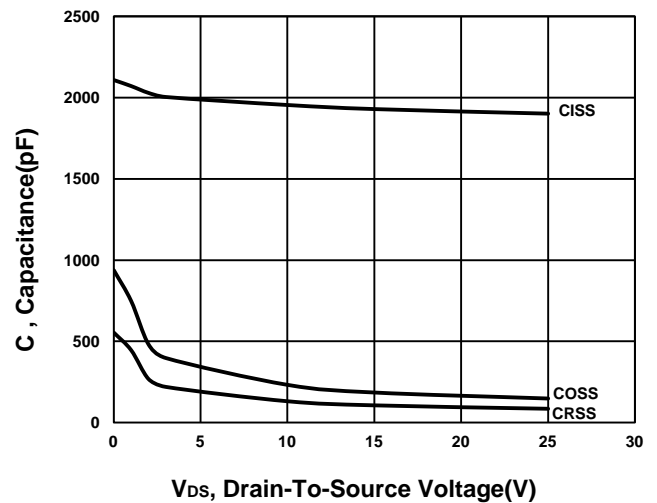
**Transfer Characteristics**



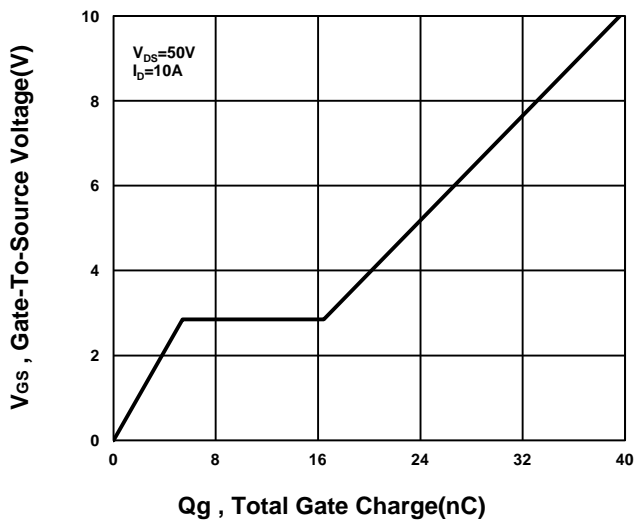
**On-Resistance VS Temperature**



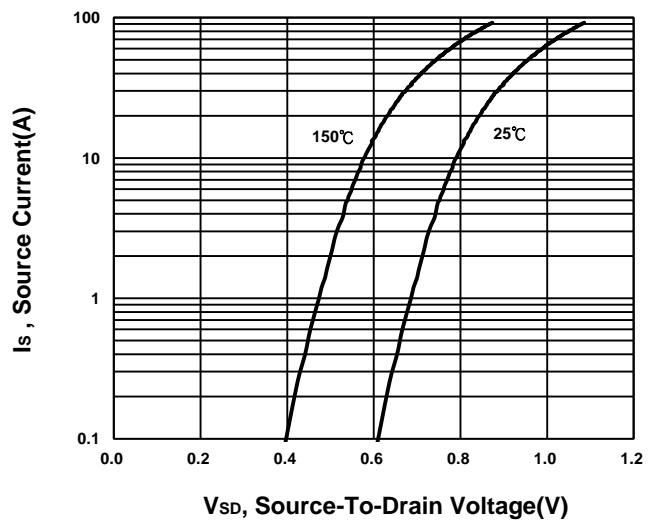
**Capacitance Characteristic**



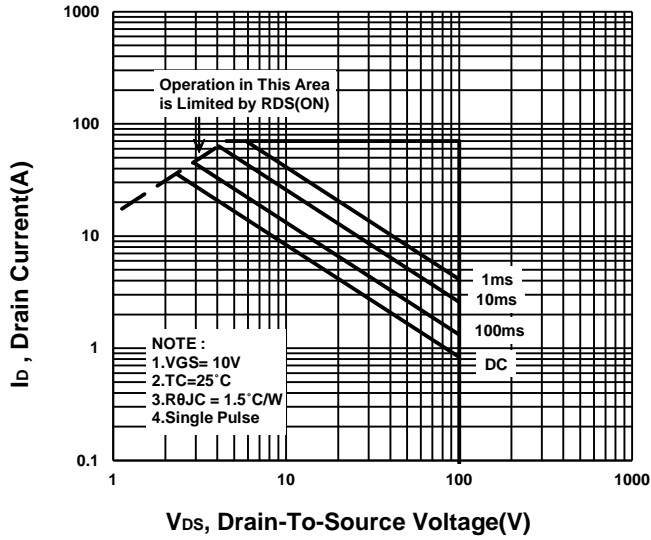
**Gate charge Characteristics**



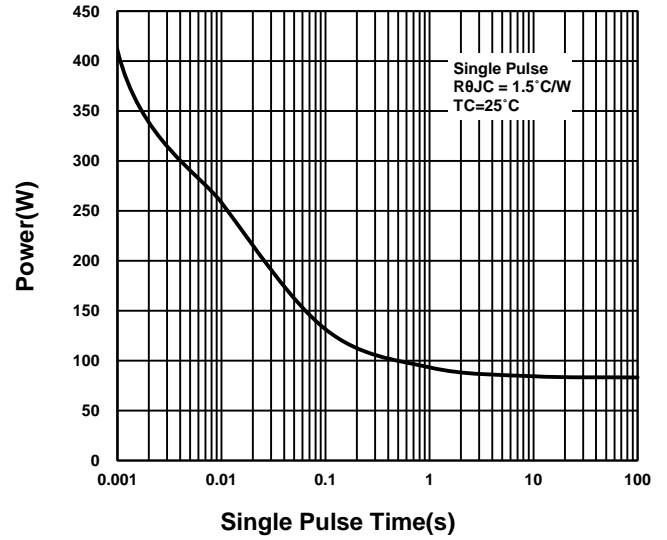
**Source-Drain Diode Forward Voltage**



**Safe Operating Area**



**Single Pulse Maximum Power Dissipation**



**Transient Thermal Response Curve**

